

## DP8212/DP8212M 8-Bit Input/Output Port

### General Description

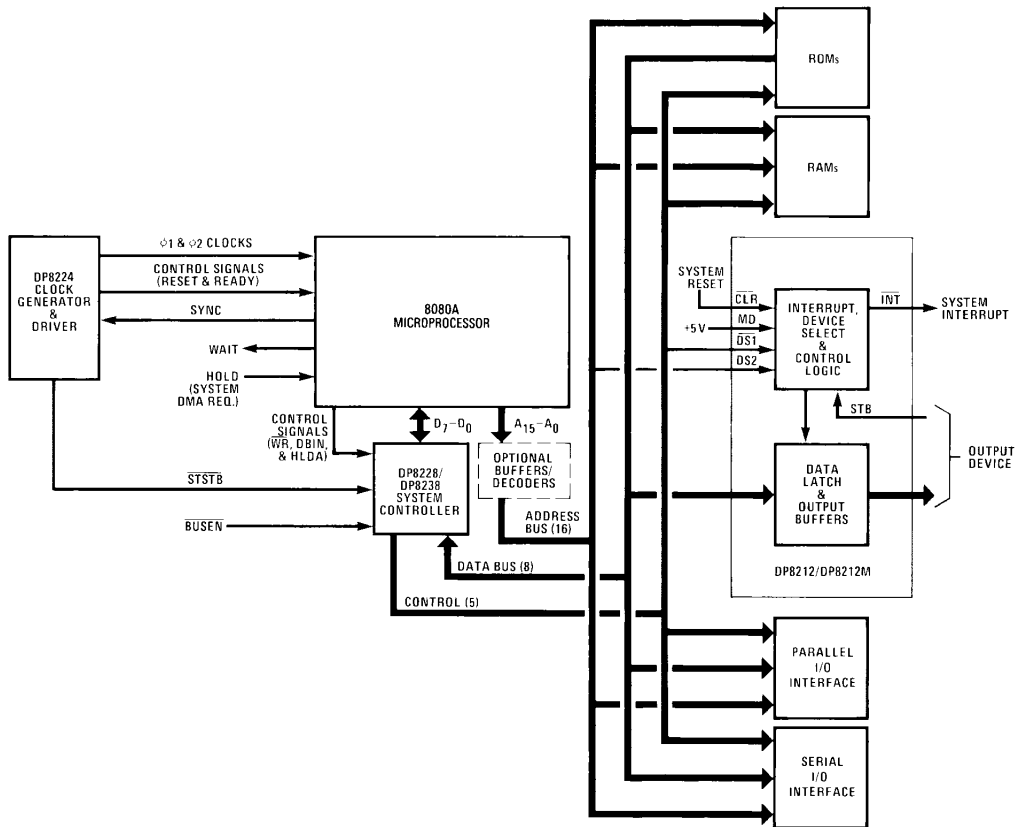
The DP8212/DP8212M is an 8-bit input/output port contained in a standard 24-pin dual-in-line package. The device, which is fabricated using Schottky Bipolar technology, is part of National Semiconductor's 8080A support family. The DP8212/DP8212M can be used to implement latches, gated buffers, or multiplexers. Thus, all of the major peripheral and input/output functions of a microcomputer system can be implemented with this device.

The DP8212/DP8212M includes an 8-bit latch with TRI-STATE® output buffers, and device selection and control logic. Also included is a service request flip-flop for the generation and control of interrupts to the microprocessor.

### Features

- 8-Bit data latch and buffer
- Service request flip-flop for generation and control of interrupts
- 0.25 mA input load current
- TRI-STATE TTL output drive capability
- Outputs sink 15 mA
- Asynchronous latch clear
- 3.65V output for direct interface to INS8080A
- Reduces system package count by replacing buffers, latches, and multiplexers in microcomputer systems

### 8080A Microcomputer Family Block Diagram



TL/F/6824-1

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## Absolute Maximum Ratings

If Military/Aerospace specified devices are required, please contact the National Semiconductor Sales Office/Distributors for availability and specifications.

Storage Temperature	-65°C to +160°C
All Output or Supply Voltages	-0.5V to +7V
All Input Voltages	-1.0V to 5.5V
Output Currents	125 mA
Maximum Power Dissipation* at 25°C	
Cavity Package	1903 mW
Molded Package	2005 mW

\*Derate cavity package 12.7 mW/°C above 25°C; derate molded package 16.0 mW/°C above 25°C.

## Operating Conditions

	Min	Max	Units
Supply Voltage (V <sub>CC</sub> )			
DP8212M	4.50	5.50	V <sub>DC</sub>
DP8212	4.75	5.25	V <sub>DC</sub>
Operating Temperature (T <sub>A</sub> )			
DP8212M	-55	+125	°C
DP8212	0	+75	°C

Note: Maximum ratings indicate limits beyond which permanent damage may occur. Continuous operation at these limits is not intended and should be limited to those conditions specified under DC electrical characteristics.

## Electrical Characteristics

Min ≤ T<sub>A</sub> ≤ Max, Min ≤ V<sub>CC</sub> ≤ Max, unless otherwise noted

Symbol	Parameter	Conditions	Min	Typ	Max	Units
I <sub>F</sub>	Input Load Current, STB, DS2, $\overline{\text{CLR}}$ , DI <sub>1</sub> -DI <sub>8</sub> Inputs	V <sub>F</sub> = 0.45V			-0.25	mA
I <sub>F</sub>	Input Load Current, MD Input	V <sub>F</sub> = 0.45V			-0.75	mA
I <sub>F</sub>	Input Load Current, $\overline{\text{DS1}}$ Input	V <sub>F</sub> = 0.45V			-1.0	mA
I <sub>R</sub>	Input Leakage Current STB, DS2, $\overline{\text{CLR}}$ , DI <sub>1</sub> -DI <sub>8</sub> Inputs	V <sub>R</sub> = V <sub>CC</sub> Max			10	μA
I <sub>R</sub>	Input Leakage Current, MD Input	V <sub>R</sub> = V <sub>CC</sub> Max			30	μA
I <sub>R</sub>	Input Leakage Current, $\overline{\text{DS1}}$ Input	V <sub>R</sub> = V <sub>CC</sub> Max			40	μA
V <sub>C</sub>	Input Forward Voltage Clamp	I <sub>C</sub> = -5 mA			-1	V
V <sub>IL</sub>	Input "Low" Voltage	DP8212M			0.08	V
		DP8212			0.85	V
V <sub>IH</sub>	Input "High" Voltage		2.0			V
V <sub>OL</sub>	Output "Low" Voltage	I <sub>OL</sub> = 10 mA	DP8212M		0.45	V
		I <sub>OL</sub> = 15 mA	DP8212		0.45	V
V <sub>OH</sub>	Output "High" Voltage	I <sub>OH</sub> = 0.5 mA	DP8212M	3.40	4.0	V
		I <sub>OH</sub> = 1.0 mA	DP8212	3.65	4.0	V
I <sub>SC</sub>	Short-Circuit Output Current	V <sub>O</sub> = 0V, V <sub>CC</sub> = 5V	-15		-75	mA
I <sub>O</sub>	Output Leakage Current, High Impedance State	V <sub>O</sub> = 0.45V/V <sub>CC</sub> Max			20	μA
I <sub>CC</sub>	Power Supply Current	DP8212M		90	145	mA
		DP8212		90	130	mA

## Capacitance\*

F = 1 MHz, V<sub>BIAS</sub> = 2.5V, V<sub>CC</sub> = 5V, T<sub>A</sub> = 25°C

Symbol	Parameter	Min	Typ	Max	Units
C <sub>IN</sub>	DS1, MD Input Capacitance		9	12	pF
C <sub>IN</sub>	DS2, $\overline{\text{CLR}}$ , STB, DI <sub>1</sub> -DI <sub>8</sub> Input Capacitance		5	9	pF
C <sub>OUT</sub>	DO1-DO8 Output Capacitance		8	12	pF

\*This parameter is sampled and not 100% tested.

## Switching Characteristics $\text{Min} \leq T_A \leq \text{Max}, \text{Min} \leq V_{CC} \leq \text{Max}$

Symbol	Parameter	Conditions	DP8212M		DP8212		Units
			Min	Max	Min	Max	
$t_{PW}$	Pulse Width		40		30		ns
$t_{PD}$	Data to Output Delay	(Note 1)		30		30	ns
$t_{WE}$	Write Enable to Output Delay	(Note 1)		50		40	ns
$t_{SET}$	Data Set-Up Time		20		15		ns
$t_H$	Data Hold Time		30		20		ns
$t_R$	Reset to Output Delay	(Note 1)		55		40	ns
$t_S$	Set to Output Delay	(Note 1)		35		30	ns
$t_E$	Output Enable/Disable Time	(Note 2)		50		45	ns
$t_C$	Clear to Output Delay	(Note 1)		65		55	ns

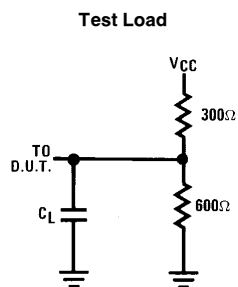
Note 1:  $C_L = 30 \text{ pF}$

Note 2:  $C_L = 30 \text{ pF}$  except for DP8212M

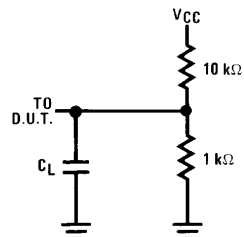
$t_E \text{ (DISABLE)} C_L = 5 \text{ pF}$

## Switching Conditions

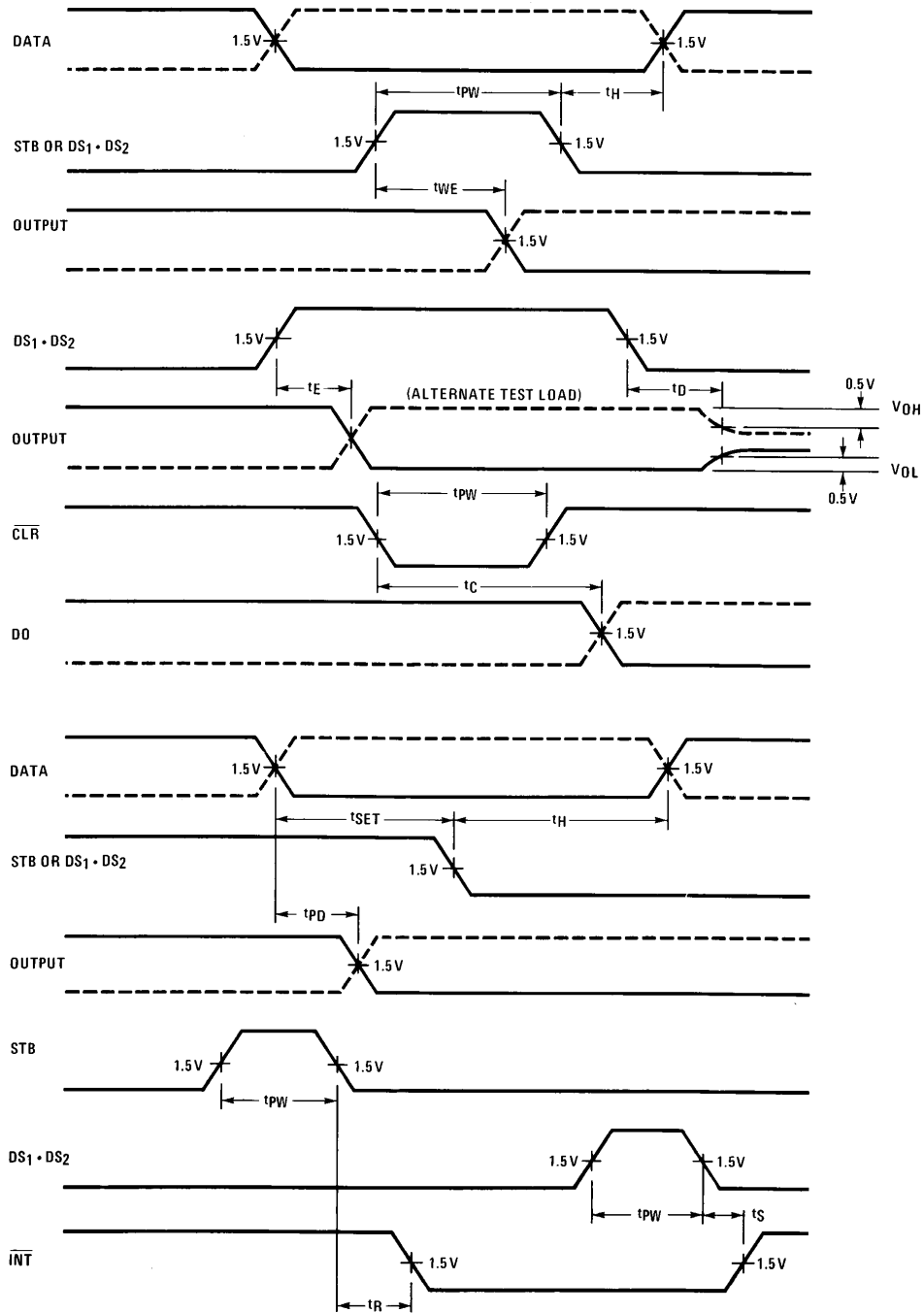
1. Input Pulse Amplitude = 2.5V.
2. Input Rise and Fall Times = 5 ns.
3. Between 1V and 2V Measurements made at 1.5V with 15 mA & 30 pF Test Load.
4.  $C_L$  includes jig and probe capacitance.
5.  $C_L = 30 \text{ pF}$ .
6.  $C_L = 30 \text{ pF}$  except for DP8212M  $t_E \text{ (DISABLE)} C_L = 5 \text{ pF}$



**Alternate Test Load  
(Refer to Timing Diagram)**

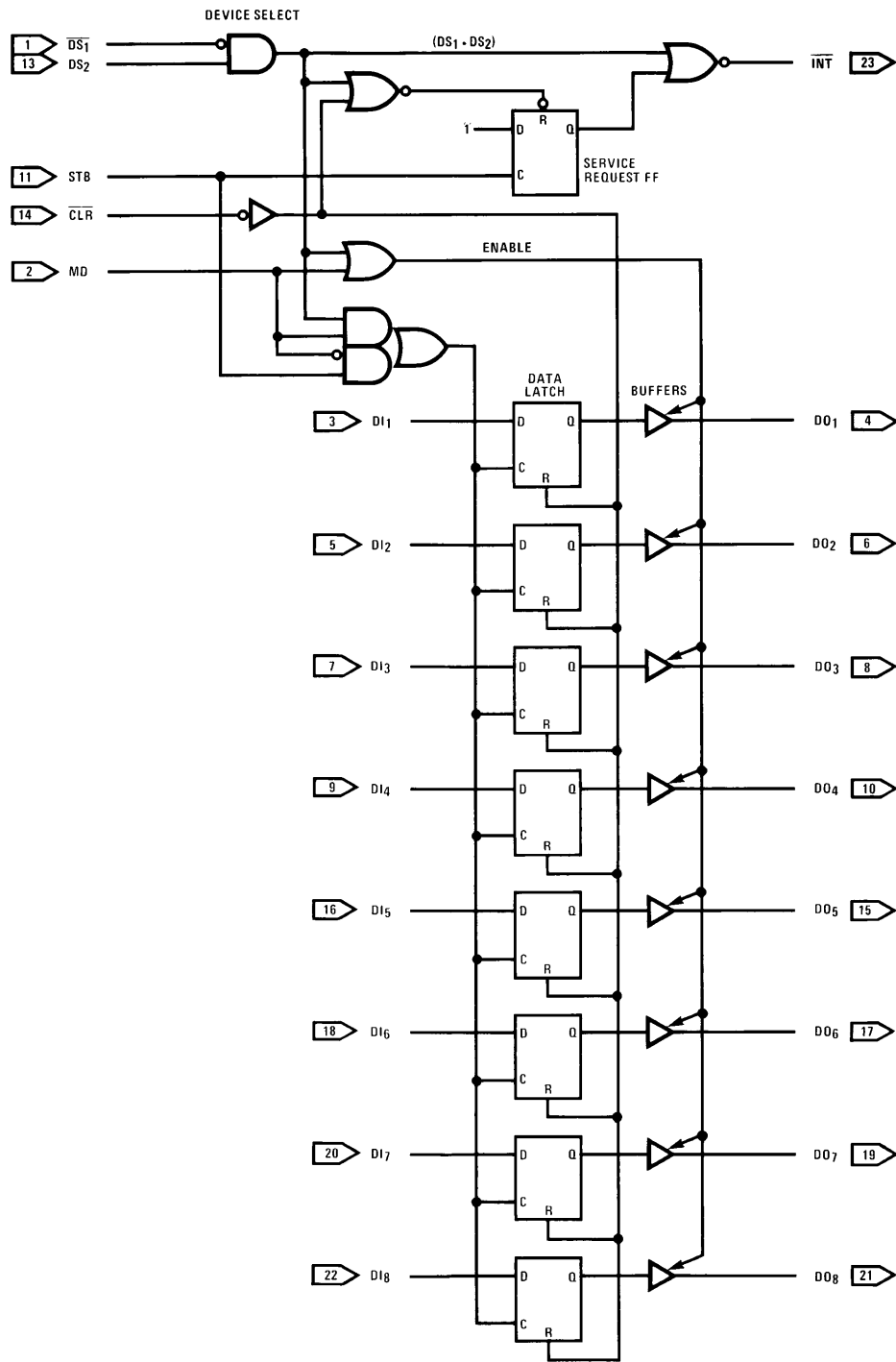


# Timing Diagram



TL/F/6824-4

# Logic Diagram



TL/F/6824-5

## Logic Tables

Logic Table A

STB	MD	(DS <sub>1</sub> •DS <sub>2</sub> )	Data Out Equals
0	0	0	TRI-STATE
1	0	0	TRI-STATE
0	1	0	DATA LATCH
1	1	0	DATA LATCH
0	0	1	DATA LATCH
1	0	1	DATA IN
0	1	1	DATA IN
1	1	1	DATA IN

$\overline{\text{CLR}}$   $\downarrow$  resets data latch to the output low state.

The data latch clock is level sensitive, a low level clock latches the data.

Logic Table B

$\overline{\text{CLR}}$	(DS <sub>1</sub> •DS <sub>2</sub> )	STB	Q*	$\overline{\text{INT}}$
0 RESET	0	0	0	1
1	0	0	0	1
1	0	$\downarrow$	1	0
1	1 RESET	0	0	0
1	0	0	0	1

\*Internal Service Request flip-flop.

## Functional Pin Definitions

The following describes the function of all the DP8212/DP8212M input/output pins. Some of these descriptions reference internal circuits.

### INPUT SIGNALS

**Device Select ( $\overline{\text{DS}}_1$ , DS<sub>2</sub>):** When  $\overline{\text{DS}}_1$  is low and DS<sub>2</sub> is high, the device is selected. The output buffers are enabled and the service request flip-flop is asynchronously reset (cleared) when the device is selected.

**Mode (MD):** When high (output mode), the output buffers are enabled and the source of the data latch clock input is the device selection logic (DS<sub>1</sub> • DS<sub>2</sub>). When low (input mode), the state of the output buffers is determined by the device selection logic (DS<sub>1</sub> • DS<sub>2</sub>) and the source of the data latch clock input is the strobe (STB) input.

**Strobe (STB):** Used as data latch clock input when the mode (MD) input is low (input mode). Also used to synchronously set the service request flip-flop, which is negative edge triggered.

**Data In (DI<sub>1</sub>–DI<sub>8</sub>):** Eight-bit data input to the data latch, which consists of eight D-type flip-flops. Incorporating a level sensitive clock while the data latch clock input is high, the Q output of each flip-flop follows the data input. When the clock input returns low, the data latch stores the data input. The clock input high overrides the clear ( $\overline{\text{CLR}}$ ) input data latch reset.

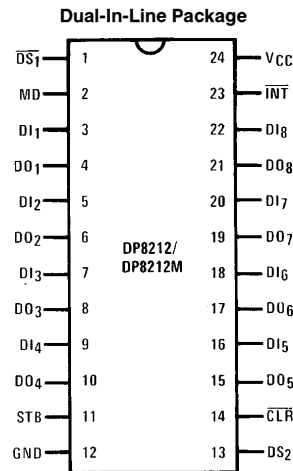
**Clear ( $\overline{\text{CLR}}$ ):** When low, asynchronously resets (clears) the data latch and the service request flip-flop. The service request flip-flop is in the non-interrupting state when reset.

### OUTPUT SIGNALS

**Interrupt ( $\overline{\text{INT}}$ ):** Goes low (interrupting state) when either the service request flip-flop is synchronously set by the strobe (STB) input or the device is selected.

**Data Out (DO<sub>1</sub>–DO<sub>8</sub>):** Eight-bit data output of data buffers, which are TRI-STATE, non-inverting stages. These buffers have a common control line that either enables the buffers to transmit the data from the data latch outputs or disables the buffers by placing them in the high-impedance state.

## Connection Diagram

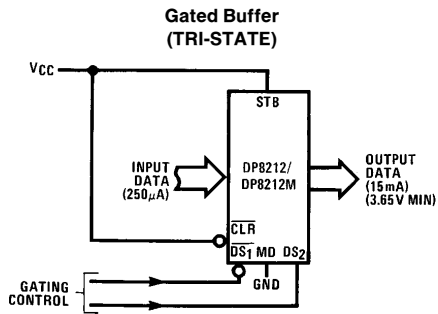


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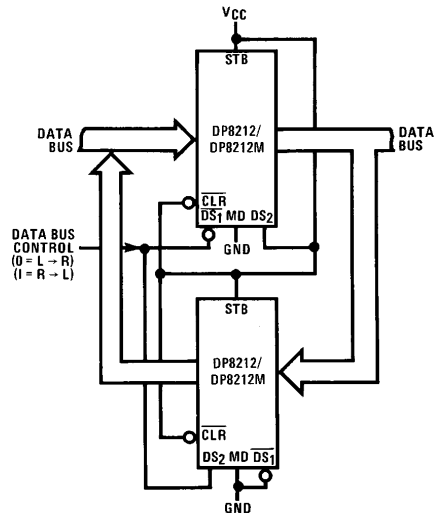
### Top View

Order Number DP8212J, DP8212N  
or DP8212MJ  
See NS Package Number J24A or N24A

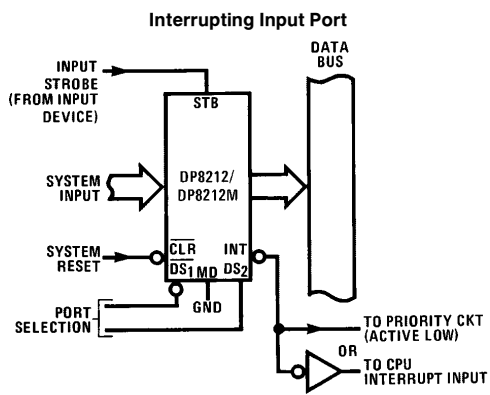
# Applications in Microcomputer Systems



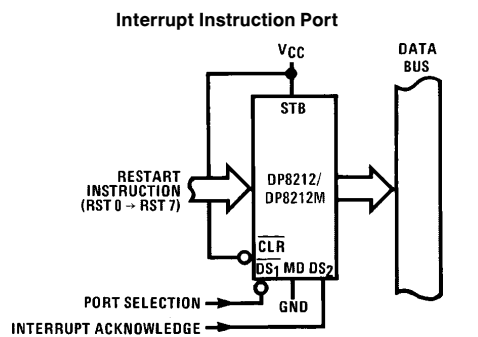
TL/F/6824-7



TL/F/6824-8



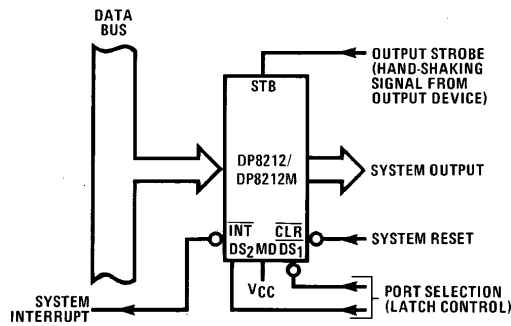
TL/F/6824-9



TL/F/6824-10

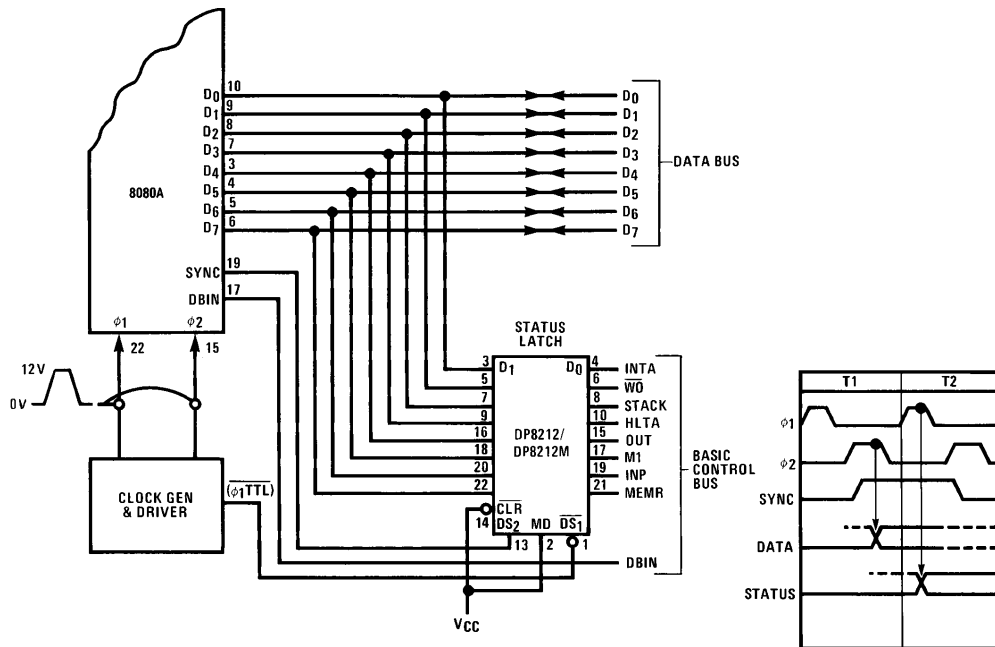
# Applications in Microcomputer Systems (Continued)

## Output Port (with Hand-Shaking)



TL/F/6824-11

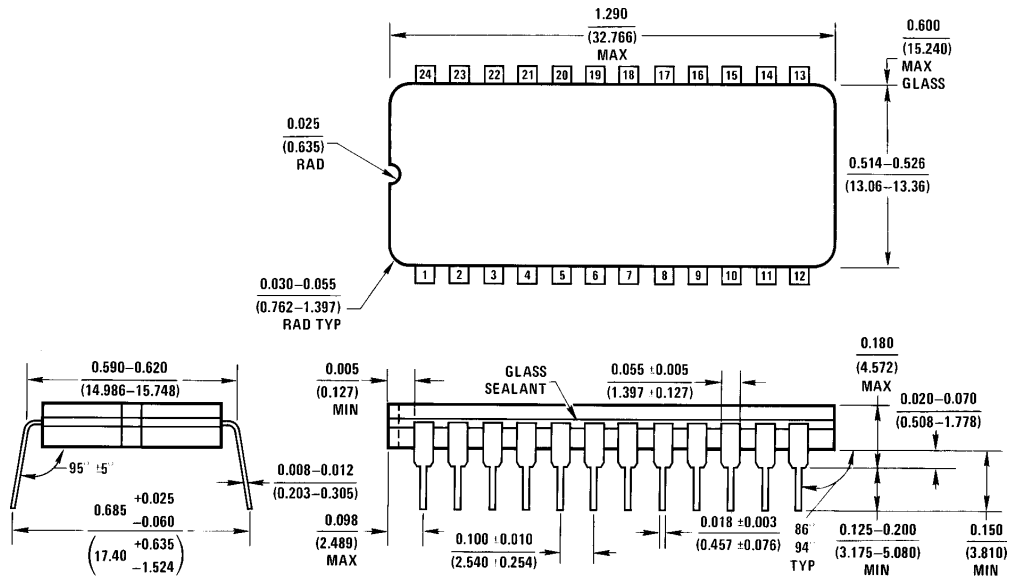
## INS8080A Status Latch



TL/F/6824-12



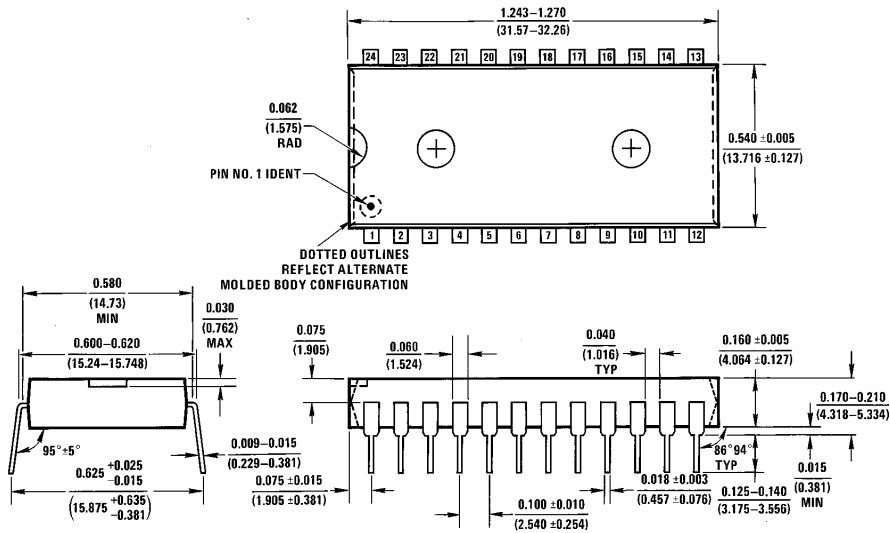
**Physical Dimensions** inches (millimeters)



**Ceramic Dual-In-Line Package (J)**  
**Order Number DP8212J or DP8212MJ**  
**NS Package Number J24A**

J24A (REV H)

**Physical Dimensions** inches (millimeters) (Continued)



**Molded Dual-In-Line Package (N)**  
**Order Number DP8212N**  
**NS Package Number N24A**

N24A (REV E)

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DP8212MJ - <http://www.ti.com/product/dp8212mj?HQS=TI-null-null-dscatalog-df-pf-null-wwe>

DP8212N - <http://www.ti.com/product/dp8212n?HQS=TI-null-null-dscatalog-df-pf-null-wwe>